

Description

Features

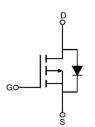
- V_{DS}= -50V, I_D= -0.13A
 - $R_{DS(ON)} < 3.6\Omega @ V_{GS} = -10V$
 - $R_{DS(ON)}$ < 5.40 @ V_{GS} = -4.5V
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead free product is acquired

Application

- PWM Applications
- Load Switch
- Power Management







Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
VSM84A-S2	VSM84A	TAPING	SOT-23-3	7inch	3000	180000

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		-50	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Continuous Drain Current	T _A = 25℃	-0.13	Α
		T _A = 100°C	-0.08	Α
I _{DM}	Pulsed Drain Current note1		-0.52	Α
P _D	Power Dissipation	T _A = 25℃	0.225	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		556	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	$^{\circ}\mathbb{C}$



Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units		
Off Characteristic								
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-50	-	-	V		
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -50V, V _{GS} =0V,	-	-	-1	μA		
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA		
On Charac	cteristics							
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-0.8	-1.5	-2.5	V		
	Static Drain-Source on-Resistance	V _{GS} = -10V, I _D = -0.13A	-	2.2	3.6			
$R_{DS(on)}$	note2	V _{GS} = -4.5V, I _D = -0.1A	-	2.6	5.4	Ω		
Dynamic (Characteristics							
C _{iss}	Input Capacitance	05)/)/ 05)/	-	30	-	рF		
Coss	Output Capacitance	V_{DS} = -25V, V_{GS} =0V,	-	10	-	pF		
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	5	-	pF		
Qg	Total Gate Charge	V - 25V I - 0.12A	-	4.5	-	nC		
Q_{gs}	Gate-Source Charge	V_{DS} = -25V, I_D = -0.13A, V_{GS} = -10V	-	0.8	-	nC		
Q_{gd}	Gate-Drain("Miller") Charge	7 VGS10V	-	1.2	-	nC		
Switching	Characteristics							
t _{d(on)}	Turn-on Delay Time		-	2.5	-	ns		
t _r	Turn-on Rise Time	V_{DD} = -25V, I_{D} = -0.1A,	-	1	-	ns		
t _{d(off)}	Turn-off Delay Time	V_{GS} = -10V, R_{GEN} =2.5 Ω	-	16	-	ns		
t _f	Turn-off Fall Time]	-	8	-	ns		
Drain-Sou	rce Diode Characteristics and Maxi	mum Ratings						
Is	Maximum Continuous Drain to Source Diode Forward Current			_	-0.13	Α		
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	-0.52	Α		
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -0.13A	-	-0.8	-1.2	V		

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



Typical Performance Characteristics

Figure1: Output Characteristics

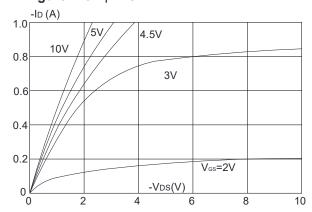


Figure 3:On-resistance vs. Drain Current

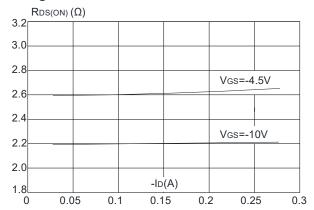


Figure 5: Gate Charge Characteristics

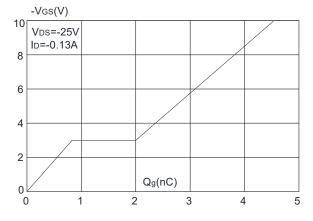


Figure 2: Typical Transfer Characteristics

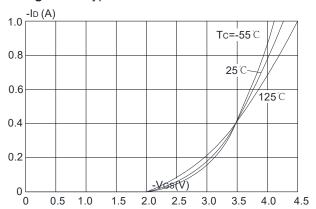


Figure 4: Body Diode Characteristics

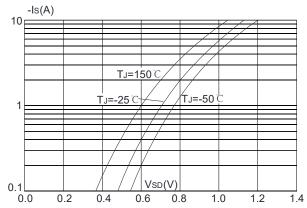


Figure 6: Capacitance Characteristics

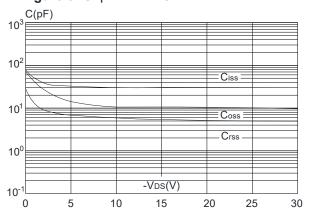




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

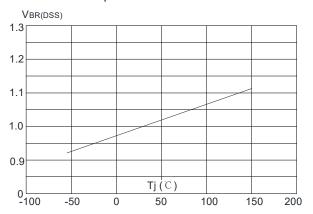


Figure 9: Maximum Safe Operating Area

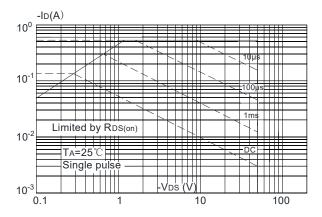


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

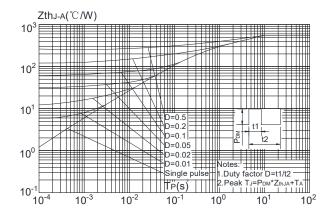


Figure 8: Normalized on Resistance vs. Junction Temperature

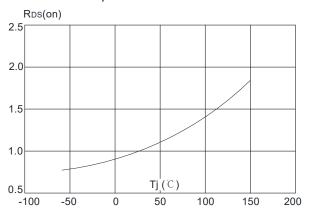
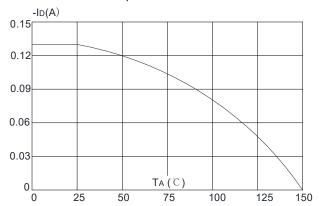


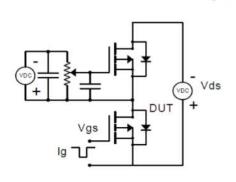
Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

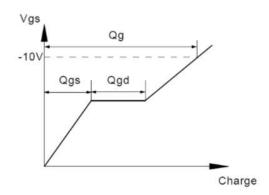




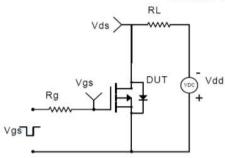
Test Circuit

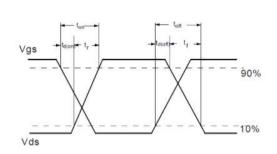
Gate Charge Test Circuit & Waveform



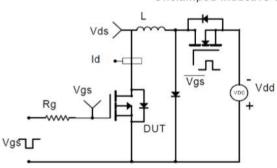


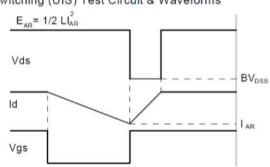
Resistive Switching Test Circuit & Waveforms





Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms

